

PROGRAM

PROGRAM

October 24, 2017

- 09:00 Welcome
- 09:10 Overview “**LOMID**”
U. Vogel (Fraunhofer FEP, Germany)
- 09:40 Overview “**LUMENTILE**”
G. Giuliani (University of Pavia, Italy)
- 09:50 **LUMENTILE** – “Hybrid large area systems R2R manufacturing”
K. Keranen (VTT, Finland)
- 10:10 **LUMENTILE** – “Light management solutions for large-area backlighting”
G. Giuliani (University of Pavia, Italy)
- 10:30 *Coffee*
- 11:00 Overview “**ROLL-OUT**”
A. Alastalo (VTT, Finland)
- 11:20 **ROLL-OUT** – “Thin film sensors and integration for automotive and packaging solutions”
M. Jank (Fraunhofer IISB, Germany)
- 11:40 Overview “**LORIX**”
A. Martinent-Beaumont (CEA, France)
- 12:00 **LORIX** – “Challenges for industrializing OTFT for TOLAE applications”
O. Trovarelli (Plastic Logic GmbH, Germany)
- 12:20 *Lunch*
- 13:20 Overview “**TransFlexTeg**”
I. Ferreira (University Lisboa, Portugal)
- 13:30 **TransFlexTeg** – “Large-area distributed thermocouple concept for thermal distribution mapping”
Taneli Juntunen (Aalto University, Finland)
- 13:50 **TransFlexTeg** – “Wireless sensor system based on transparent and flexible TEGs”
K. Jaakkola (VTT, Finland)
- 14:10 *Coffee*

- 14:30 Overview “**ALABO**”
U. Klotzbach (Fraunhofer IWS, Germany)
- 14:40 **ALABO** – “Process Innovation and Impact”
M. Anderson (Heliatek, Germany)
- 15:00 **ALABO** – “Scribing organic Photovoltaic on thin film barrier with laser sources”
T. Kuntze (Fraunhofer IWS, Germany)
- 15:20 Poster Session
- 16:30 Lab Tour Fraunhofer IWS & FEP
- 18:30 *Dinner (requested: Watzke Brauereiausshank am Goldenen Reiter, Hauptstraße 1, 01067 Dresden)*

October 25, 2017

- 09:00 Welcome
- 09:05 Overview “**OptIntegral**”
E. Piqueras (EURECAT, Spain)
- 09:25 **OptIntegral** – “R2R hybrid integration process”
J. Eveliina (VTT, Finland)
- 09:45 **OptIntegral** – “Industrial integration of printed electronics (via injection molding)”
E. Escudero (EURECAT, Spain)
- 10:05 **HAPPINESS** – “Haptic components printed on plastic foil for Automotive applications”
A. Latour (CEA Grenoble, France)
- 10:35 **SmartEEs** – “A Sustainable Marketplace for the Adoption, Ramp-up and Transfer of Emerging Electronic Solutions”
C. May (Fraunhofer FEP, Germany)
- 11:05 Overview “**PiScale**”
C. Keibler (Fraunhofer FEP, Germany)
- 11:35 Panel discussion and summary
Real-life testing / validation for applicability to industrial and societal challenges
- 12:30 *Lunch*

INDUSTRIAL WORKSHOP

„THIN, ORGANIC AND LARGE AREA ELECTRONICS TECHNOLOGIES”

October 24–25, 2017

Fraunhofer IWS Dresden, Germany



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INVITATION

Advanced Thin, Organic and Large Area Electronics (TOLAE) technologies is an emerging technology and forms the basis for advanced products in large area electronics. TOLAE offers a platform for creating advanced technology and products that could penetrate a multitude of markets, including light weight, flexible and/or stretchable. TOLAE suits large market sectors such as the textile, automotive, health, paper, plastic, advertising or construction industries. Horizon 2020 is investing heavily in the translation of thin, organic and large-area electronics from the lab to the market. Every TOLAE project benefits from a consortium consisting of academic and industrial partners, often representing the entire value chain. The involvement of multiple stakeholders – from Research and Development to SME, large companies and Leading Network for the Next Generation of Thin, Organic as well as Large Area Electronics are poised to push up and commercialize results.

We will give you an overview about the latest results on European funded projects.

**ALABO | HAPPINESS | LOMID | LORIX |
LUMENTILE | OptIntegral | PiScale |
ROLL-OUT | TransFlexTeg | SmartEEs**



ORGANIZATION

Location: Fraunhofer-Institut für Werkstoff- und Strahltechnik
Winterbergstraße 28
01277 Dresden, Germany

www.iws.fraunhofer.de/en

Workshop language: English

Workshop fee: 280 €
90 € for project member
230 € for members of OE-A, OES and AFELIM (payable on receipt of the invoice)

Registration: To register please use the form on www.iws.fraunhofer.de/TOLAE

Registration deadline: **October 10, 2017**

Cancellation of registration is possible by October 17, 2017. Afterwards full costs will be charged.

Contact: Dr. Udo Klotzbach
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PROJECTS



Advanced Laser Ablation on Barrier films for Organic and large area electronic devices (**ALABO**)



Haptic Printed and Patterned Interfaces for Sensitive Surface (**HAPPINESS**)



Large cost-effective OLED microdisplays and their applications (**LOMID**)



Large Organic Robust Imager for X-Ray Sensing (**LORIX**)



LUMinous ElectroNic TILE (**LUMENTILE**)



Advertisement displays manufactured by hybrid in-mould integration (**OptIntegral**)



Bringing flexible organic electronics to pilot innovation scale (**PiScale**)



High-performance, Flexible, AUTonomous Systems manufactured with Unique, Industrial ROLL-to-roll equipments (**ROLL-OUT**)



Large area transparent thin film thermoelectric devices for smart window and flexible applications (**TransFlexTeg**)

SMART Emerging Electronics Servicing DIH (**SmartEEs**)